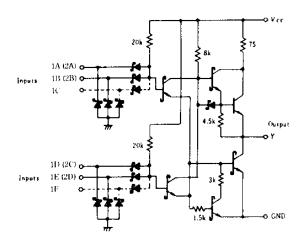
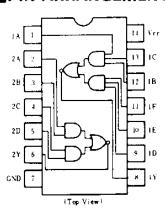
■CIRCUIT SCHEMATIC(½)



PIN ARRANGEMENT



TELECTRICAL CHARACTERISTICS ($Ta = -20 \sim +75$ °C)

Item	Symbol	Test Conditions		min	typ*	max	Unit
	VIH			2.0	_	_	v
Input voltage	V11.			-		0.8	V
Output voltage	Von	$V_{CC} = 4.75 \text{V}, V_{IL} = 0.8 \text{V}, I_{OH} = -400 \mu \text{A}$		2.7	_	_	V
			Io L = 8mA	_	_	0.5	v
	Voj.	$V_{CC} = 4.75 \text{V}$, $V_{IH} = 2 \text{V}$	$I_{OL} = 4mA$	_	_	0.4	
Input current	Ith	$V_{CC}=5.25$ V, $V_{I}=2.7$ V			_	20	μA
	In	$V_{CC} = 5.25 \text{V}, V_{f} = 0.4 \text{V}$			_	-0.4	m A
	- Ii	$V_{CC} = 5.25$ V, $V_f = 7$ V		-		0.2	m A
Short-circuit output current	los	$V_{CC} = 5.25 \text{V}$		- 20	_	-100	mA
Supply current	Ісси	V 05W			0.8	1.6	mА
	<i>Icci</i> .	$V_{CC} = 5.25$ V		_	1.4	2.8	ША
Input clamp voltage	Vik	$V_{CC} = 4.75 \text{V}, I_{IN} = -18 \text{mA}$		_	_	-1.5	V

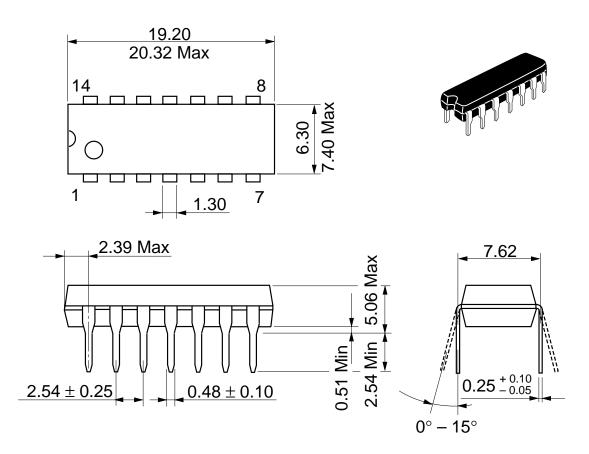
^{*} V_{CC}=5V, Ta=25°C

ESWITCHING CHARACTERISTICS ($V_{CC} = 5V$, $T_a = 25^{\circ}C$)

Item	Symbol	Test Conditions	min	typ	max	Unit
Propagation delay time	tPLH	$C_L = 15 \text{pF}, R_L = 2 \text{k}\Omega$	_	12	20	ns
	ten.		_	12.5	20	
			4			

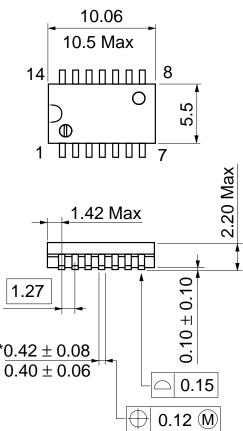
Note) Refer to Test Circuit and Waveform of the Common Item

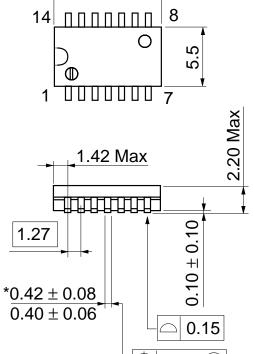
Unit: mm



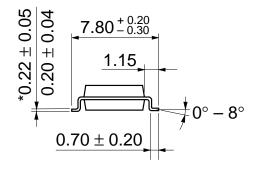
Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm





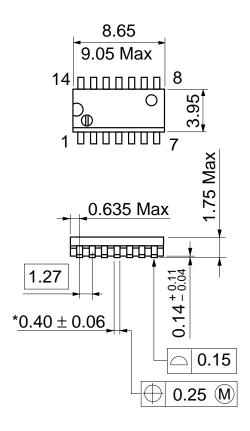




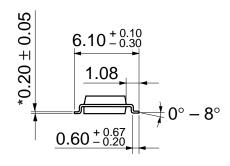
Hitachi Code	FP-14DA
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.23 g

Dimension	including	the	plating	thickness
Bas	se materia	al dir	mensio	1

Unit: mm







Hitachi Coo	de	FP-14DN	
JEDEC		Conforms	
EIAJ		Conforms	
Weight (refe	erence value)	0.13 g	

*Pd plating

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